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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	840
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7n3f45c4

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	-0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	-0.5	3.4	V
V <sub>I</sub>	DC input voltage	-0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	-55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	-65	150	°C
I <sub>OUT</sub>	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

### **Maximum Allowed Overshoot and Undershoot Voltage**

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
		3.0	0.189	
		2.5	0.208	
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C
	Willout recalibration	1.5	0.273	1
		1.2	0.317	

#### Note to Table 13:

(1) Valid for a  $V_{\text{CCIO}}$  range of  $\pm 5\%$  and a temperature range of  $0^\circ$  to  $85^\circ\text{C}.$ 

### **Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices** 

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

### **Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I <sub>IOPIN (DC)</sub>	DC current per I/O pin	300 μΑ
I <sub>IOPIN (AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX (DC)</sub>	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX (DC)</sub>	DC current per transceiver receiver pin	50 mA

### Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

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### **Internal Weak Pull-Up Resistor**

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V <sub>CC10</sub> Conditions (V) <sup>(3)</sup>	Value <sup>(4)</sup>	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R <sub>PU</sub>	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

#### Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k $\Omega$ .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than  $V_{\text{CCIO}}$ .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

### I/O Standard Specifications

Table 17 through Table 22 list the input voltage ( $V_{IH}$  and  $V_{IL}$ ), output voltage ( $V_{OH}$  and  $V_{OL}$ ), and current drive characteristics ( $I_{OH}$  and  $I_{OL}$ ) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The  $V_{OL}$  and  $V_{OH}$  values are valid at the corresponding  $I_{OH}$  and  $I_{OL}$ , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012\_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

1/0		V <sub>CCIO</sub> (V)		VII	_(V)	V <sub>IH</sub>	(V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub>	I <sub>OH</sub>
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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# **Switching Characteristics**

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

# **Transceiver Performance Specifications**

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/ Description	Conditions	Trai	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL								
Sidiludius	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) (8)	_	40	—	710	40		710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	_	100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_		400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	—	400	_	_	400	_	_	400	- ps
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled) <sup>(3)</sup>	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/1000/900/850 (2)			1050/	00/850 <sup>(2)</sup>	mV	
	RX reference clock pin	1.	.0/0.9/0	.85 <sup>(4)</sup>	1.	1.0/0.9/0.85 (4)			1.0/0.9/0.85 (4)		
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	sceive Grade	r Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1		2	_	_	2		_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_				-	1.4-V an	ıd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85- $\Omega$ setting		85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting		150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V <sub>OCM</sub> (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V <sub>OCM</sub> (DC coupled)	_		650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30	_	160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	_	160	30	_	160	30		160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)  $^{(1)}$ 

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit		
Description		Min	Тур	Max	Min	Тур	Max	1		
	100 Hz	_	_	-70	_	_	-70			
Transmitter REFCLK	1 kHz	_	_	-90		_	-90			
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz		
MHz) <sup>(18)</sup>	100 kHz	_	_	-110	_	_	-110			
	≥1 MHz		_	-120	_		-120	1		
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(15)</sup>	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)		
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω		
Transceiver Clocks										
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz		
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz		
Receiver										
Supported I/O Standards	_	— 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps		
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps		
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps		
Absolute V <sub>MAX</sub> for a receiver pin <sup>(3)</sup>	GT channels	_	_	1.2	_	_	1.2	V		
Absolute V <sub>MIN</sub> for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V		
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V		
differential input voltage V <sub>ID</sub> (diff p-p) before device configuration <sup>(20)</sup>	GX channels				(8)					
	GT channels									
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) after device configuration (16), (20)	$V_{CCR\_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V		
oomiguration ', ' /	GX channels			<u> </u>	(8)		•	•		
Minimum differential	GT channels	200	_	_	200		_	mV		
eye opening at receiver serial input pins <sup>(4)</sup> , <sup>(20)</sup>	GX channels				(8)					

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)  $^{(1)}$ 

Symbol/	Conditions		Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors (7)	GT channels	_	100	_	_	100	_	Ω
	85-Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels (19)	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V <sub>ICM</sub> (AC coupled)	GT channels	_	650	_	_	650	_	mV
	VCCR_GXB = 0.85 V or 0.9 V	_	600	_	_	600	_	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth	_	700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth	_	750	_	_	750	_	mV
t <sub>LTR</sub> <sup>(9)</sup>	_	_	_	10	_	_	10	μs
t <sub>LTD</sub> <sup>(10)</sup>	_	4	_	_	4	_	_	μs
t <sub>LTD_manual</sub> (11)		4	_	_	4	_	_	μs
t <sub>LTR_LTD_manual</sub> (12)		15	_	_	15	_	_	μs
Run Length	GT channels	_	_	72	_	_	72	CID
nuii Leiigiii	GX channels				(8)			
CDR PPM	GT channels	_	_	1000	_	_	1000	± PPM
ODITITIVI	GX channels				(8)			
Programmable	GT channels	_	_	14	_	_	14	dB
equalization (AC Gain) <sup>(5)</sup>	GX channels				(8)			
Programmable	GT channels	_	_	7.5	_	_	7.5	dB
DC gain <sup>(6)</sup>	GX channels				(8)			
Differential on-chip termination resistors <sup>(7)</sup>	GT channels		100	_	_	100	_	Ω
Transmitter	· '		•			•	•	
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600	_	12,500	600		12,500	Mbps

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- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

# **Core Performance Specifications**

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

### **Clock Tree Specifications**

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance							
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit				
Global and Regional Clock	717	650	580	MHz				
Periphery Clock	550	500	500	MHz				

#### Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

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# **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range ( $-40^{\circ}$  to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
INPFD	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>vco</sub> <sup>(9)</sup>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
f <sub>OUT</sub>	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>out_ext</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>оитриту</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
FCOMP	External feedback clock compensation time	_		10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)		_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

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Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
<b>→</b> (3) (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> ≥ 100 MHz)	_	_	0.15	UI (p-p)
t <sub>INCCJ</sub> (3), (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>OUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5 <sup>(1)</sup>	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )		_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>OUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ 10</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>outccj_10</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>FOUTCCJ_IO</sub>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}}$ < 100 MHz)	_	_	60	mUI (p-p)
t <sub>CASC_OUTPJ_DC</sub>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>VALUE</sub>	Numerator of Fraction	128	8388608	2147483648	_

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY	C4,I4			
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t <sub>DUTY</sub>	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t <sub>RISE</sub> & t <sub>FALL</sub>	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150		_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_		300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f <sub>HSDRDPA</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)		(8)	(6)		(8)	(6)	_	(8)	Mbps
f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
DPA Mode														
DPA run length	_		_	1000 0			1000 0	_		1000 0	_	_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	1 — —		_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	,													
Sampling Window	_	_	_	300	_		300	_		300	_	_	300	ps

#### Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1  $^{(1)}$ 

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nconfig low to conf_done low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nconfig high to nstatus high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	N-1/f <sub>DCLK</sub> <sup>(5)</sup>	_	S
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>R</sub>	Input rise time	_	40	ns
t <sub>F</sub>	Input fall time	_	40	ns
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(4)</sup>	_	_

#### Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the  $t_{status}$  specification. If nstatus is not monitored, follow the  $t_{cfack}$  specification.

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# **Active Serial Configuration Timing**

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

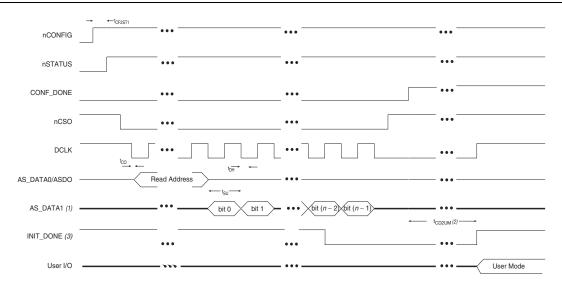
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

#### Notes to Table 52:

- This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



### Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS\_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or  ${\tt CLKUSR}$  pin.
- (3) After the option bit to enable the  $INIT\_DONE$  pin is configured into the device, the  $INIT\_DONE$  goes low.

Table 53 lists the timing parameters for AS  $\times 1$  and AS  $\times 4$  configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CO</sub>	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t <sub>SU</sub>	Data setup time before falling edge on DCLK	1.5	_	ns
t <sub>H</sub>	Data hold time after falling edge on DCLK	0	_	ns

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Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter	Available	Min	Fast	Slow Model								
(1)	Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

#### Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.
- (2) Minimum offset does not include the intrinsic delay.

# **Programmable Output Buffer Delay**

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit
		0 (default)	ps
D	Rising and/or falling edge	25	ps
D <sub>OUTBUF</sub>	delay	50	ps
		75	ps

### Note to Table 59:

# **Glossary**

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions			
Α					
В	_	_			
С					
D	_	_			
E	_				
	f <sub>HSCLK</sub>	Left and right PLL input clock frequency.			
F	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.			
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.			

<sup>(1)</sup> You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

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Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	<del>-</del>
1		
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus).  JTAG Timing Specifications:  TMS  TDI  TCK  TJPSU  TJ
K L M N	_	
P	PLL Specifications	Diagram of PLL Specifications (1)  CLKOUT Pins  Four Core Clock  Reconfigurable in User Mode  External Feedback  Note:  (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.
Q	_	<del>-</del>
R	R <sub>L</sub>	Receiver differential input discrete resistor (external to the Stratix V device).
	_ <u>-</u>	

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Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
		■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.
		■ Added the I3YY speed grade to the V <sub>CC</sub> description in Table 6.
		■ Added the I3YY speed grade to V <sub>CCHIP_L</sub> , V <sub>CCHIP_R</sub> , V <sub>CCHSSI_L</sub> , and V <sub>CCHSSI_R</sub> descriptions in Table 7.
		■ Added 240-Ω to Table 11.
		■ Changed CDR PPM tolerance in Table 23.
		■ Added additional max data rate for fPLL in Table 23.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.
		■ Changed CDR PPM tolerance in Table 28.
		■ Added additional max data rate for fPLL in Table 28.
		■ Changed the mode descriptions for MLAB and M20K in Table 33.
		■ Changed the Max value of f <sub>HSCLK_OUT</sub> for the C2, C2L, I2, I2L speed grades in Table 36.
November 2014	3.3	■ Changed the frequency ranges for C1 and C2 in Table 39.
		■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.
		■ Added note about nSTATUS to Table 50, Table 51, Table 54.
		■ Changed the available settings in Table 58.
		■ Changed the note in "Periphery Performance".
		■ Updated the "I/O Standard Specifications" section.
		■ Updated the "Raw Binary File Size" section.
		■ Updated the receiver voltage input range in Table 22.
		■ Updated the max frequency for the LVDS clock network in Table 36.
		■ Updated the DCLK note to Figure 11.
		■ Updated Table 23 VO <sub>CM</sub> (DC Coupled) condition.
		■ Updated Table 6 and Table 7.
		■ Added the DCLK specification to Table 55.
		■ Updated the notes for Table 47.
		■ Updated the list of parameters for Table 56.
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the "Transceiver Characterization" section
	2.8	■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59
October 2013		■ Added Figure 1 and Figure 3
		■ Added the "Transceiver Characterization" section
		■ Removed all "Preliminary" designations.

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Table 61. Document Revision History (Part 3 of 3)

Date	Version	Changes
	2.7	■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60
May 2013		■ Added Table 24, Table 48
		■ Updated Figure 9, Figure 10, Figure 11, Figure 12
February 2013	2.6	■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46
,		■ Updated "Maximum Allowed Overshoot and Undershoot Voltage"
	2.5	■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35
		■ Added Table 33
		■ Added "Fast Passive Parallel Configuration Timing"
D		■ Added "Active Serial Configuration Timing"
December 2012		■ Added "Passive Serial Configuration Timing"
		■ Added "Remote System Upgrades"
		■ Added "User Watchdog Internal Circuitry Timing Specification"
		■ Added "Initialization"
		■ Added "Raw Binary File Size"
	2.4	■ Added Figure 1, Figure 2, and Figure 3.
June 2012		■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.
		<ul><li>Various edits throughout to fix bugs.</li></ul>
		■ Changed title of document to Stratix V Device Datasheet.
		■ Removed document from the Stratix V handbook and made it a separate document.
February 2012	2.3	■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.
December 2011	2.2	■ Added Table 2–31.
December 2011		■ Updated Table 2–28 and Table 2–34.
Nevember 0011	0.1	■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.
November 2011	2.1	■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.
		■ Various edits throughout to fix SPRs.
	2.0	■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.
May 2011		■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications" title.
		■ Chapter moved to Volume 1.
		■ Minor text edits.
	1.1	■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.
December 2010		Converted chapter to the new template.
		■ Minor text edits.
July 2010	1.0	Initial release.